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**SSEC Single Wafer Technology Enables  
Thin and SEMI Wafer Wet Processing**

Horsham, PA—Meeting the demand for ultra-thin wafers to be used in advanced device packaging, Solid State Equipment Corporation has developed single wafer tooling that supports both thin and SEMI standard wafers for single wafer wet processing. The tooling enables these wafers to be processed without hardware changeover and enables standard wet processing for wet wafer cleaning, stripping, etching and photolithography.

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Thin Wafer Wet Processing and Handling for Advanced Device Packaging